

Honsu Group 2025Q3 Business Update

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- I、Company
 - II、Performance
 - III、R&D Investment
 - IV、Product Strategy
 - V、Dividend Policy
-



I 、 Company

II 、 Performance

III 、 R&D Investment

IV 、 Product Strategy

V 、 Dividend Policy



弘塑科技股份有限公司
Grand Process Technology Corporation

Y1993 Founded
Y2011 IPO (3131)
Employee : 230

□ Main Product:

**Wet Process
Equipment (Etch
/PR Strip/ Cleaner) 、
Chemical Deliver
System**



添鴻科技股份有限公司
Chemleader Corporation

Y2013 Merged
Y2002 Founded
Employee : 100

□ Main Product:

**Wet Process
Chemistry
(Etchant 、 PR
Stripper 、
Plating Additive)**



佳霖科技股份有限公司
Challentech International Corporation

Y2019 Merged
Y1987 Founded
Employee : 120

□ Main Product:

**Agent Metrology(X-
Ray 、 CSAM 、 EPD) 、
Inspection 、 Wafer
Transfer 、 Robot 、
pump Overhaul**



太引資訊系統股份有限公司
TYNE Systems Corporation

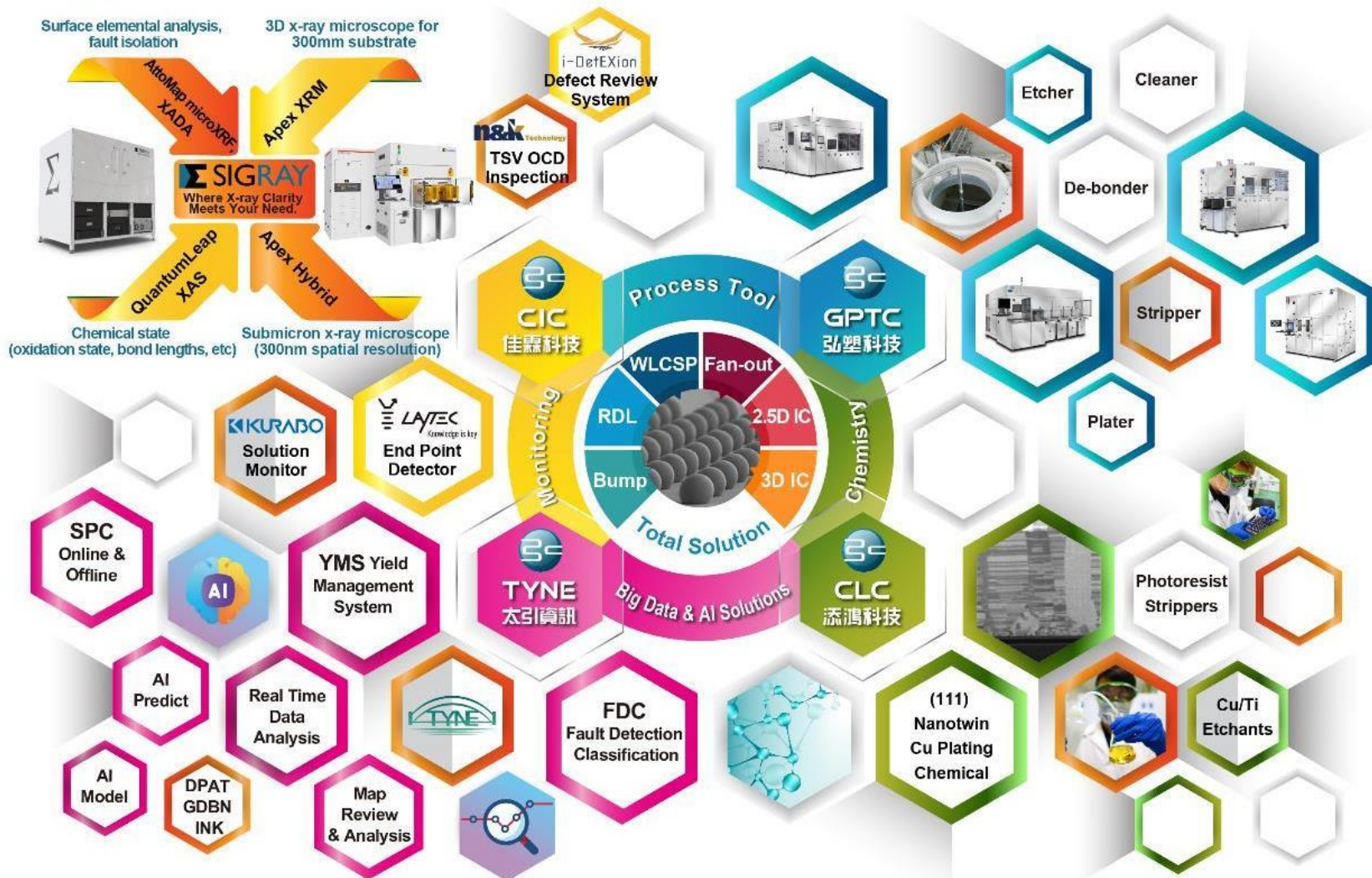
Y2018 Merged
Y2002 Founded
Employee : 30

□ Main Product:

**Software System
Design(EDA 、
SPC 、 FDC 、 Big
data) Service**



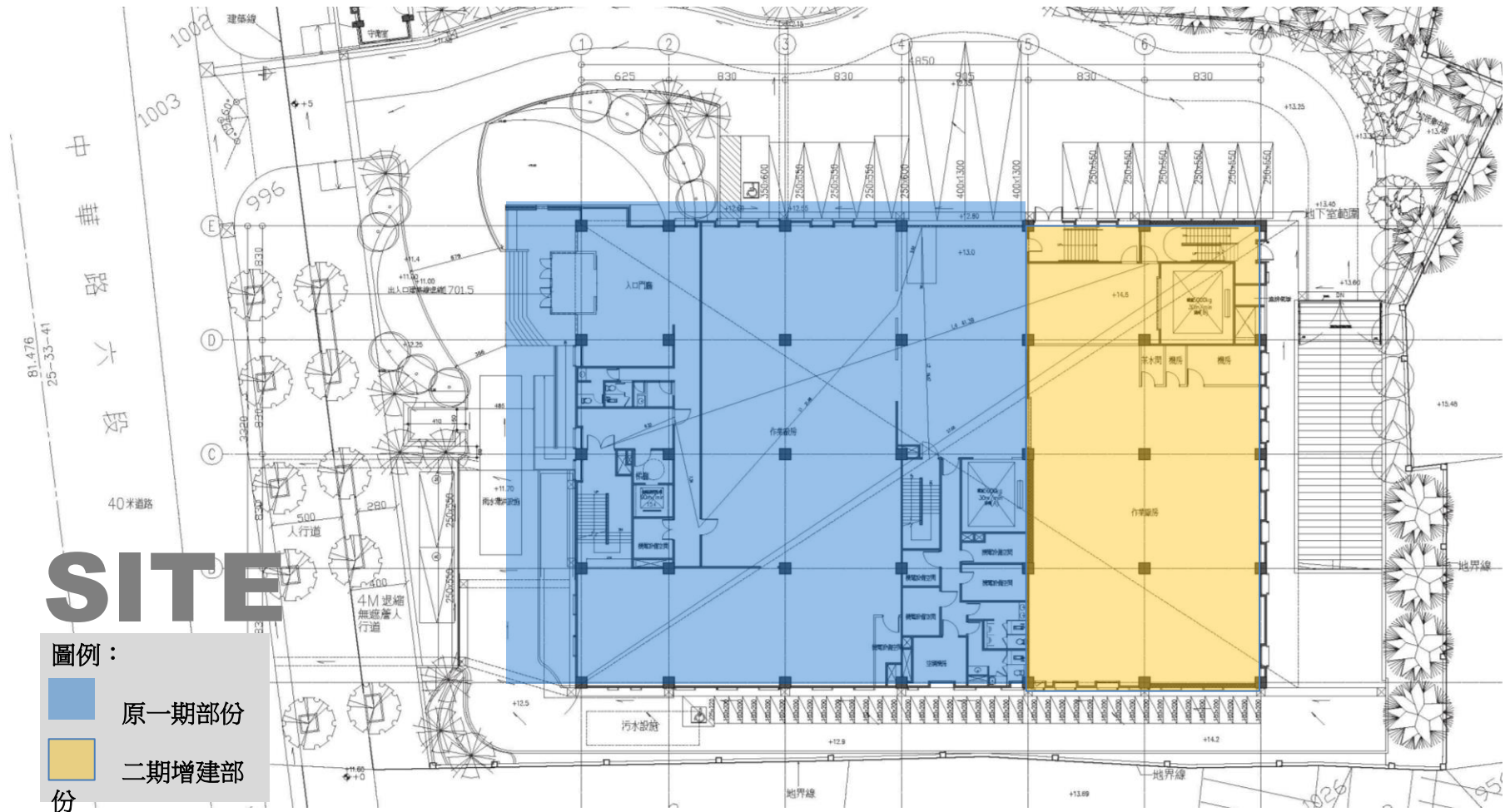
Quality Assurance Solutions to Advanced Packaging



New Factory Plan - GPTC

GPTC Phase2 Factory

- Schedule : Planned 2026/Q1 Ready for production
- Manufacturing footprint : ~ same as Phase1





I、Company

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Income Statement(By Quarter)

MNTD									
Quarter / account	1Q24	2Q24	3Q24	4Q24	1Q25	2Q25	3Q25	QoQ	YoY
Revenue	898	962	992	1,222	1,241	1,630	1,494	-8.4%	50.6%
Gross Profit	388	417	477	562	506	662	608	-8.0%	27.5%
OP Expense	215	216	228	280	230	255	291	14.3%	27.6%
OP Net Profit	174	201	249	282	277	407	317	-22.0%	27.5%
Non-OP Revenue	45	45	22	45	41	(114)	62	154.0%	176.1%
Income before Tax	218	246	271	327	318	293	379	29.5%	39.7%
Net Profit	172	205	217	251	255	205	303	47.9%	39.8%
EPS(NTD)	5.99	7.04	7.42	8.61	8.74	7.05	10.40	47.5%	40.2%
Gross Margin	43.2%	43.4%	48.1%	46.0%	40.8%	40.6%	40.7%	0.2%	-7.4%
OP Margin	19.3%	20.9%	25.1%	23.1%	22.3%	25.0%	21.2%	-3.7%	-3.9%
Margin before Tax	24.3%	25.5%	27.4%	26.8%	25.6%	18.0%	25.4%	7.4%	-2.0%

Income Statement

MNTD								
Year / account	2020	2021	2022	2023	2,024	2024 1Q~3Q	2025 1Q~3Q	YoY
Revenue	2,488	3,658	3,723	3,544	4,073	2,852	4,365	53.1%
Gross Profit	1,126	1,563	1,618	1,488	1,845	1,283	1,776	38.5%
OP Expense	593	739	859	793	939	659	776	17.6%
OP Net Profit	533	824	759	695	906	624	1,001	60.5%
Non-OP Revenue	(23)	10	175	54	141	112	(11)	-110.2%
Income before Tax	510	835	934	749	1,047	735	990	34.6%
Net Profit	397	670	722	616	846	594	763	28.5%
EPS(NTD)	13.92	23.47	25.32	21.56	29.07	20	26	28.1%
Gross Margin	45.3%	42.7%	43.5%	42.0%	45.3%	45.0%	40.7%	-4.3%
OP Margin	21.4%	22.5%	20.4%	19.6%	22.2%	21.9%	22.9%	1.1%
Margin before Tax	20.5%	22.8%	25.1%	21.1%	25.7%	25.8%	22.7%	-3.1%



I、Company

II、Performance

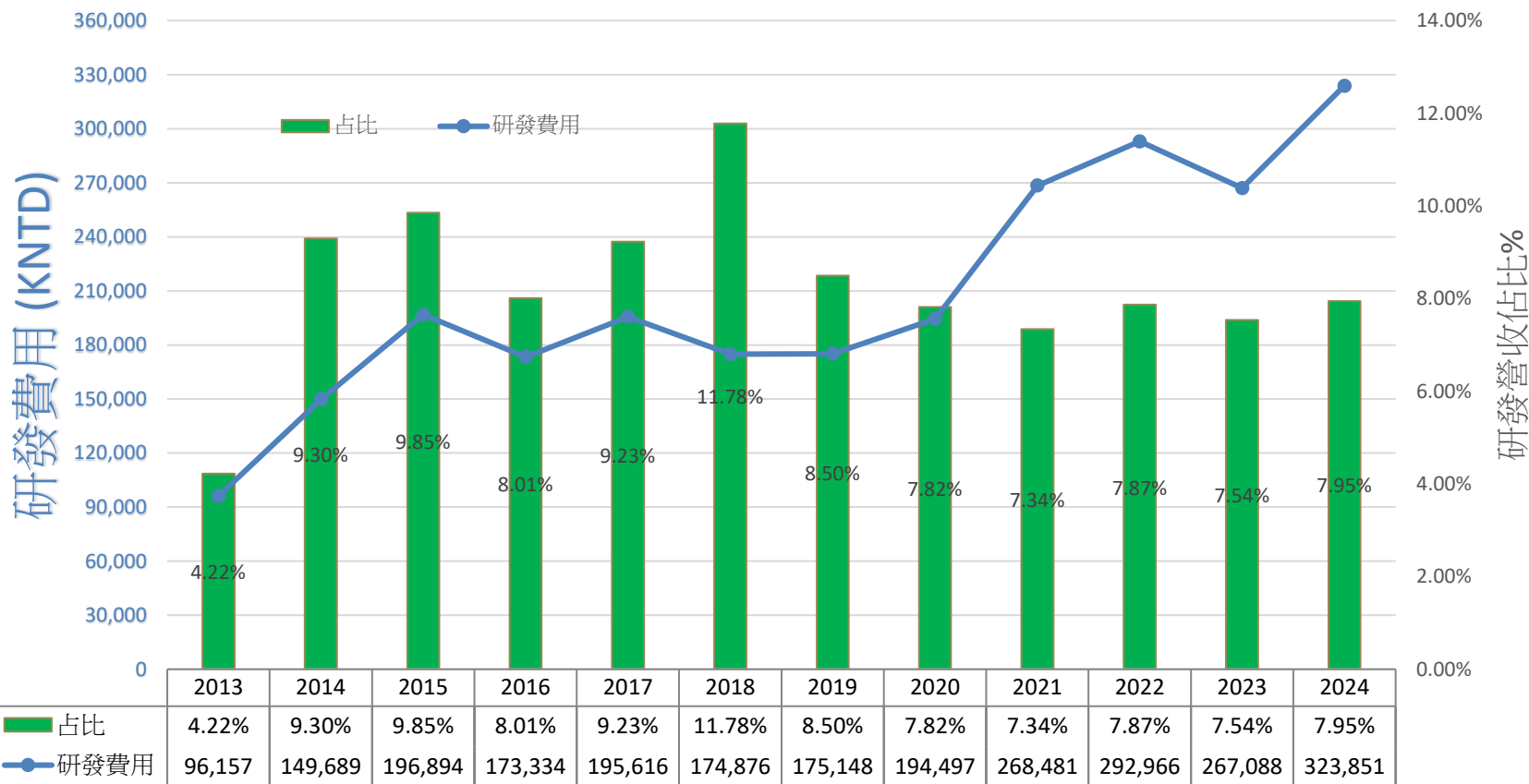
III、R&D Investment

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R&D Expense Investment

弘塑科技研發費用及營收佔比(Group)





I 、 Company

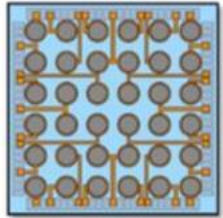
II 、 Performance

III 、 R&D Investment

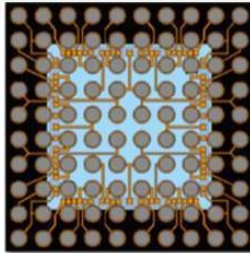
IV 、 Product Strategy

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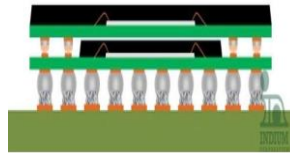
Process Application Opp.



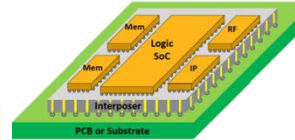
Fan-In /
WL-CSP



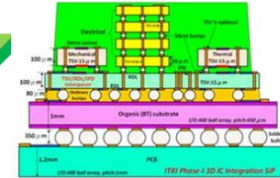
Fan-Out /
WLP/PLP



Package on
package



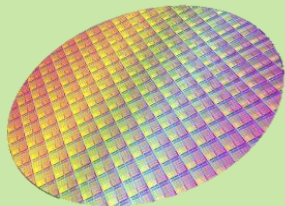
2.5D
- Fan-In/Out
- CoWoS



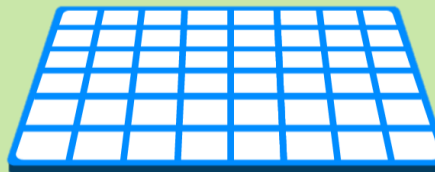
SoIC/
Hybrid Bond

*2D to 3D
Structure*

*Wide Range
Wafer Size*



75mm
100mm
125mm
150mm
200mm
300mm



310*310 mm
510*515 mm
600*600 mm

*Multi-
Application*

Advanced Package

- Flip Chip Bumping
- Fan Out Packaging
- 2.5D CoWoS
- 3D SoIC 、CPO

Compounded

- SiC
- GaAs/GaN
- InP

Automotive

- Diode
- CIS
- Micro LED

Others

- Bio Chip
- Crystal element
- IC Substrate



I、Company

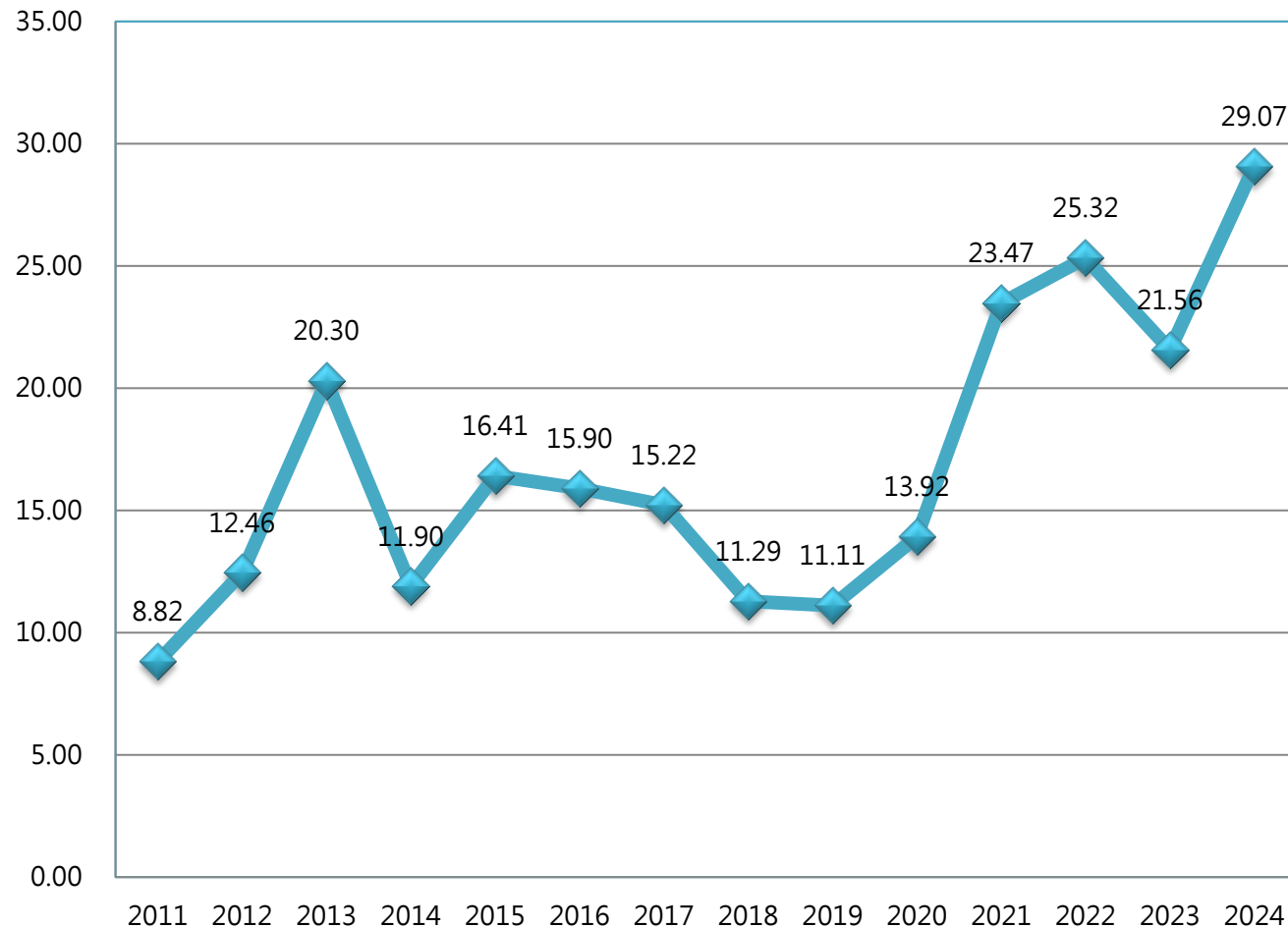
II、Performance

III、R&D Investment

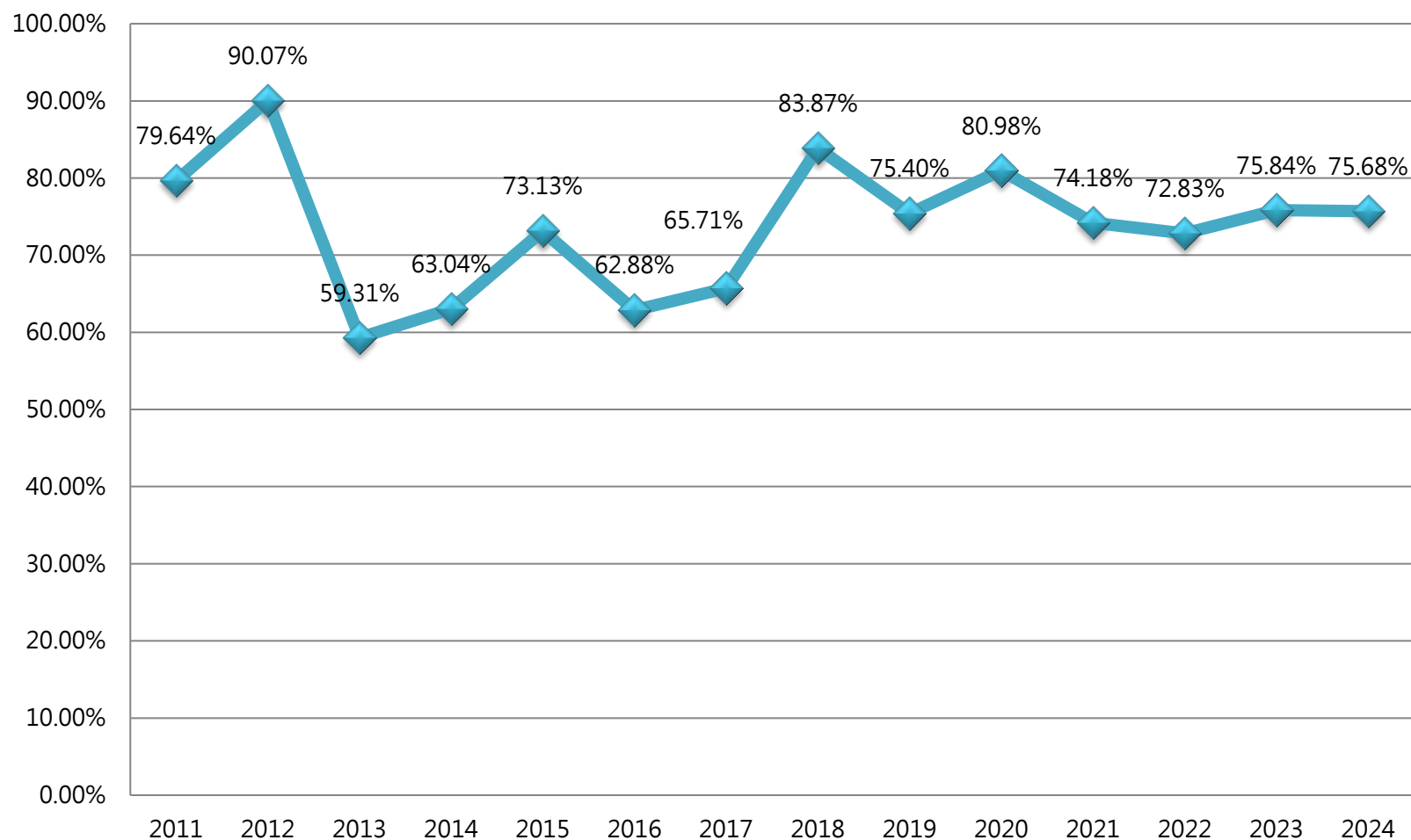
IV、Product Strategy

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歷年EPS趨勢



歷年股利配發率趨勢



THANKS

感 謝 聆 聽



弘塑集團